

# SG4016VS GaN TRANSISTOR

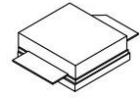
Document Number: SG4016VS  
Preliminary Datasheet V1.0

## GaN 50V, 160W, 2-3GHz RF Transistor

### Description

The SG4016VS is a 160-watt, internally matched GaN HEMT, designed for CW applications with frequencies from 2000 to 3000MHz, in typical 2.3-2.7GHz, it can deliver 160W within full band. There is no guarantee of performance when this part is used in applications designed outside of these frequencies.

**SG4016VS**



**Earless**

- Typical **CW** Performance (On Innogration fixture with device soldered):

$V_{DD} = 50$  Volts,  $I_{DQ} = 200$  mA

Freq (MHz)	Power gain (dB)	Pout (dBm)	Pout (W)	Ids (A)	Eff (%)
2300	13.07	53.07	202.8	6.51	62.30
2400	13.80	53.00	199.5	6.24	63.97
2500	14.20	52.80	190.5	5.88	64.81
2600	13.70	52.56	180.3	5.57	64.74
2700	12.90	52.20	165.9	5.28	62.86

### Applications and Features

- Suitable for broad band application in S band CW amplifier applications.
- Thermally Enhanced Industry Standard Package
- High Reliability Metallization Process
- Excellent thermal Stability and Excellent Ruggedness
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

**Important Note:** Proper Biasing Sequence for GaN HEMT Transistors

#### ■ Turning the device ON

- 1) Set VGS to the pinch-off (VP) voltage, typically -5 V
- 2) Turn on VDS to nominal supply voltage (50 V)
- 3) Increase VGS until IDS current is attained
- 4) Apply RF input power to desired level

#### ■ Turning the device OFF

- 1) Turn RF power off
- 2) Reduce VGS down to VP, typically -5 V
- 3) Reduce VDS down to 0 V
- 4) Turn off VGS

**Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
Drain--Source Voltage	$V_{DS}$	+200	Vdc
Gate--Source Voltage	$V_{GS}$	-8 to +0	Vdc
Operating Voltage	$V_{DD}$	0 to 55	Vdc
Maximum Forward Gate Current @ $T_C = 25^\circ\text{C}$	$I_{gmax}$	22	mA

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Storage Temperature Range	$T_{stg}$	-65 to +150	°C
Case Operating Temperature	$T_c$	+150	°C
Operating Junction Temperature	$T_j$	+225	°C

**Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case, $P_{OUT}=160W$ CW @3GHz by FEA	$R_{\theta JC}$	1.0	°C/W

**Table 3. Electrical Characteristics** ( $T_A = 25^\circ C$  unless otherwise noted)

**DC Characteristics**

Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS}=-8V$ ; $I_{DS}=22mA$	$V_{DSS}$	—	200	—	V
Gate Threshold Voltage	$V_{DS} = 10V$ , $I_D = 22mA$	$V_{GS(th)}$	-4		-2	V

**Load Mismatch (In Innogration Test Fixture, 50 ohm system):**  $V_{DD} = 50 Vdc$ ,  $I_{DQ} = 200 mA$ ,  $f = 3000 MHz$

VSWR 10:1 at 350W pulse CW Output Power	No Device Degradation
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## TYPICAL CHARACTERISTICS

Figure 2. Power gain, efficiency as function of Pout, Pulsed CW

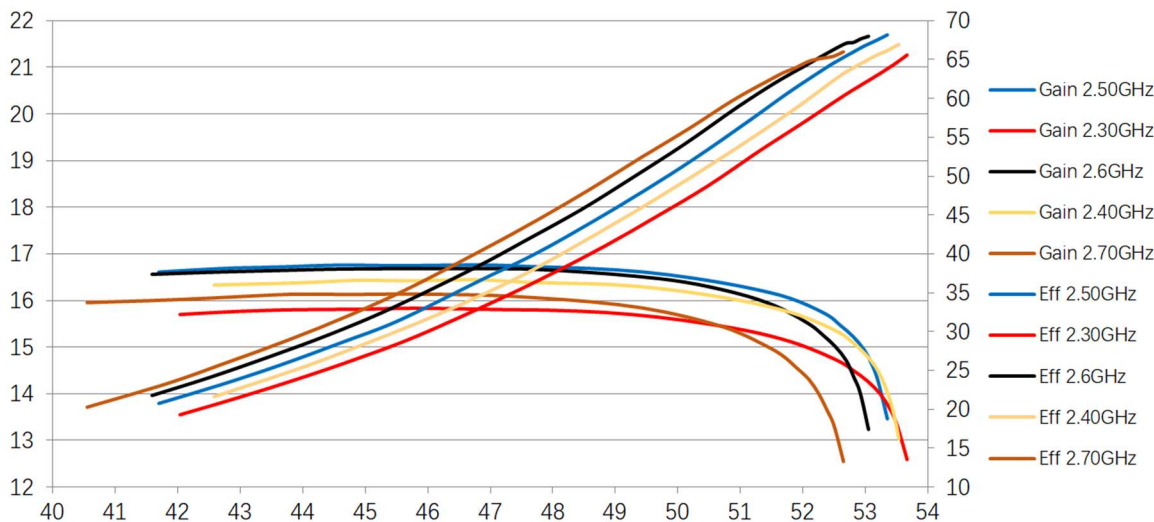


Figure 3. Test Circuit Component Layout

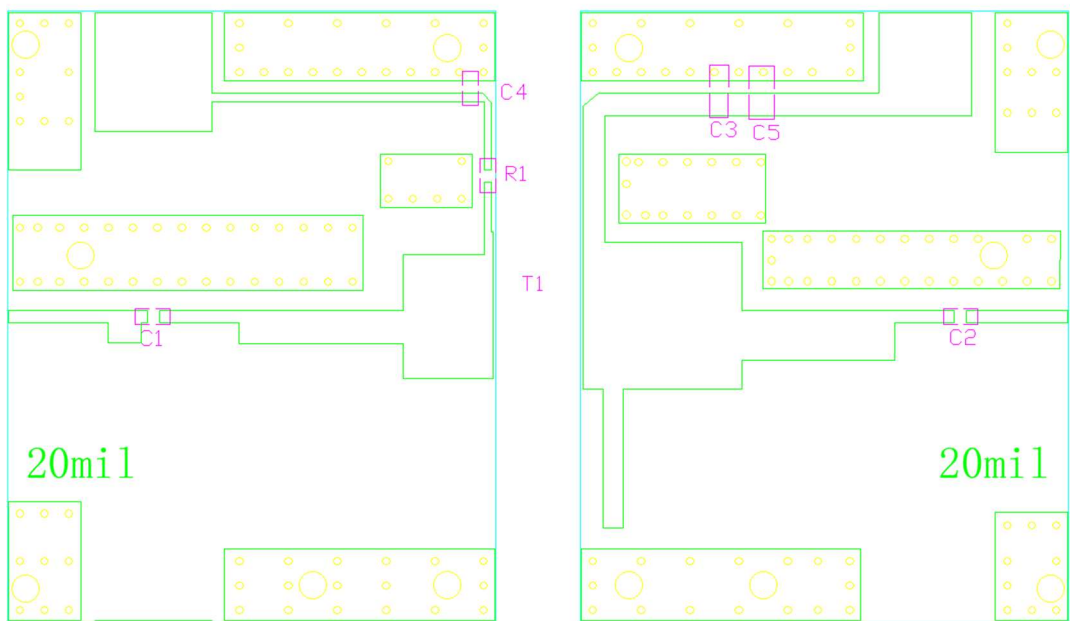
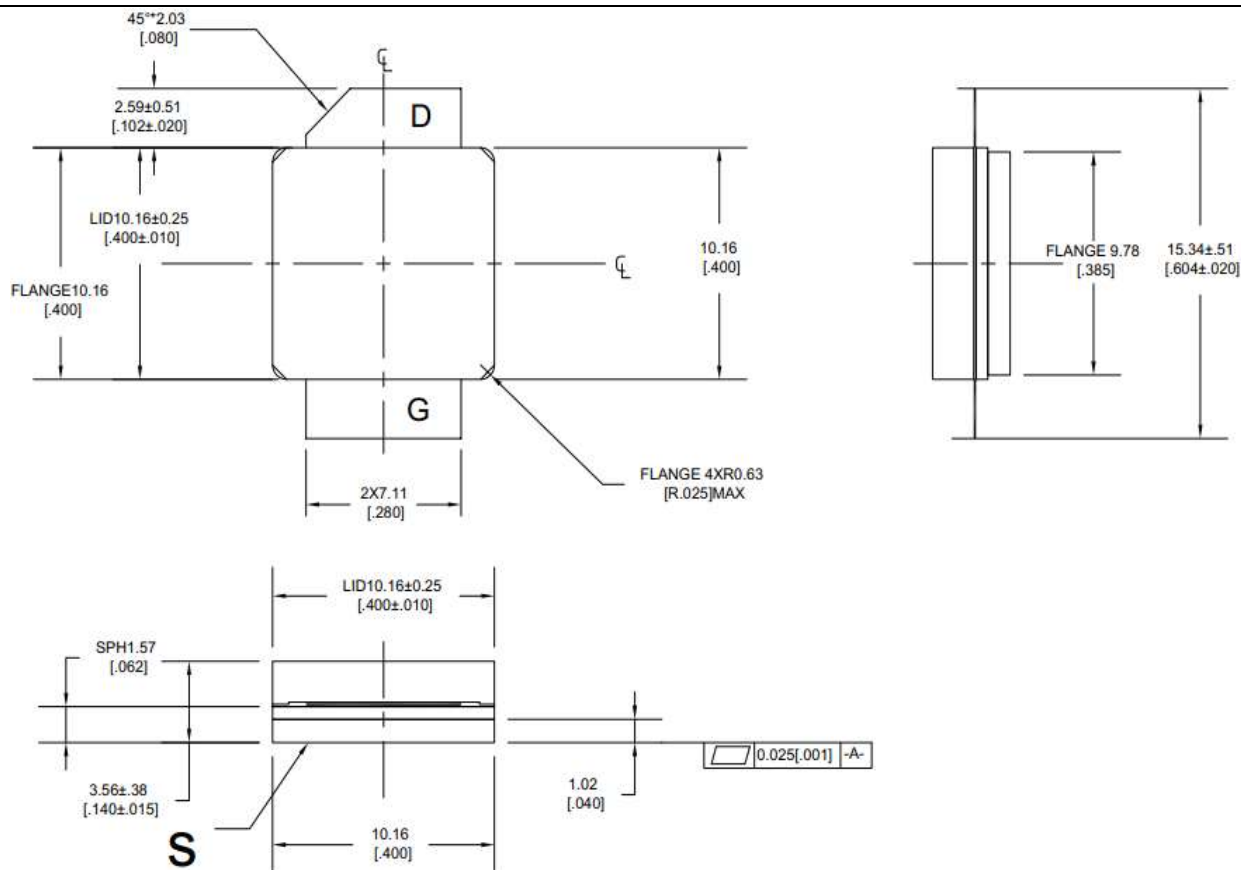


Table 4. Test Circuit Component Designations and Values

Part	Quantity	Description	Part Number	Manufacture
C1,C2,C3,C4	4	10pFHigh Q Capacitor	251SHS100BSE	TEMEX
R1	1	10 $\Omega$ Power Resistor	ESR03EZPF100	ROHM
C5	1	10uF MLCC	GRM32EC72A106ME0 5	Murata
T1	1	160W GaN Dual Transistor	SG4016VS	Innogration

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Unit: mm [inch]

Tolerance .xx +/- 0.01 .xxx +/- 0.005 inches

## Revision history

Table 5. Document revision history

Date	Revision	Datasheet Status
2024/7/3	Rev 1.0	Preliminary Datasheet

Application data based on LWH-24-25

## Notice

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